

# $HD-LINX^{TM}$ GO1515 Voltage Controlled Oscillator

# DATA SHEET

#### FEATURES

- generates 1.485GHz or 1.485/1.001GHz signal for HD-LINX™ ICs
- low current consumption
- 50Ω output impedance
- · operates from a single 5V supply
- 8 pin tape on reel

## APPLICATIONS

VCO for the following HD-LINX<sup>™</sup> ICs: GS1515, GS1522, GS1540, GS1545.

#### **ORDERING INFORMATION**

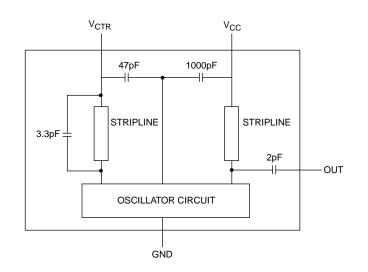
PART NUMBER	PACKAGE	TEMPERATURE
GO1515 - CTA	8 pin tape on reel	0°C to 70°C

# DESCRIPTION

The GO1515 is a self contained, miniature Voltage Controlled Oscillator (VCO) that is used in conjunction with Gennum's HD-LINX<sup>™</sup> ICs. It produces a clean 1.485GHz reference clock signal for such devices as the GS1515 HDTV Reclocker and other HD-LINX<sup>™</sup> devices. The control voltage range is from 3.10 volts to 4.65 volts and is derived from the on-chip PLLs. The GO1515 frequency can be pulled approximately 16MHz for every one volt of control.

The output level is approximately 1.0dBm with low spurious and noise content. It is designed to drive  $50\Omega$  strip lines.

The GO1515 VCO is used with the following HD-LINX<sup>™</sup> ICs; GS1515, GS1522, GS1540, GS1545 and is ordered as a separate item. The VCO requires a single 5V supply and draws a maximum of 15mA of current. It is packaged in a miniature 8-pin proprietary surface mount package and operates over the normal commercial temperature range of 0°C to +70°C.



# **BLOCK DIAGRAM**

Revision Date: March 2000

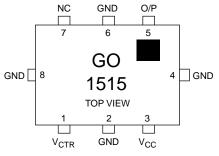
Document No. 522 - 40 - 02

# **ELECTRICAL CHARACTERISTICS**

 $V_{\rm S}$  = 5.0V ±0.25V, Temperature = 0°C to 70°C unless otherwise specified.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage	V <sub>CC</sub>		4.75	5.0	5.25	V
Supply Current	I <sub>S</sub>		-	-	15	mA
Control Voltage Range	V <sub>CTR</sub>		+3.1	-	+4.65	V
Control Voltage Sensitivity	df/dV		11	16	21	MHz/V
Operating Frequency Range	f <sub>VCO</sub>		1483.5	-	1485.5	MHz
Output Signal Level	V <sub>OUT</sub>		-2	1	+4	dBm
Signal to Noise Ratio	S/N	Signal Level: 1kHz ±8kHz Deviation = 0.3~3.0kHz	40	-	-	dB
Carrier to Noise Ratio	C/N	25kHz Separation, 1kHz Bandwidth	74	-	-	dBc
Pushing Figure		$V_{\rm S}$ = 5.0V ±0.25V, ref: $V_{\rm S}$ = 5.0V	-	±500	-	kHz
Pulling Figure		VSWR = 2.0 for all phase, ref: $50\Omega$	-	±1000	-	kHz
Temperature Stability	T <sub>COEF</sub>	$0^{\circ}$ C to $70^{\circ}$ C, ref. = $25^{\circ}$ C	-	-	±3	MHz
Spurious Response			-	-	-10	dBc
Output Impedance	Z <sub>O</sub>		-	50	-	Ω

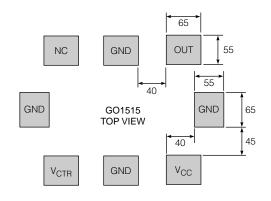
# **PIN CONNECTIONS**



NOTE: Pin numbers are arbitrary. There are no pin markings on the device itself

## **PIN DESCRIPTIONS**

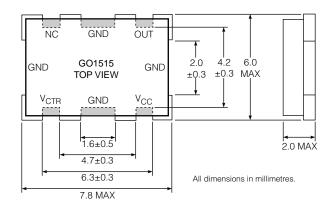
NUMBER	SYMBOL	TYPE	DESCRIPTION
2, 4, 6, 8	GND	-	Most negative power supply connections.
1	V <sub>CTR</sub>	l	Control voltage for the VCO.
3	V <sub>CC</sub>	-	Most positive power supply connection.
5	O/P	0	VCO signal output.
7	NC	-	No connection.



All dimensions are in mils 1 mil = 1/1000 inch

Fig. 1 Footprint of the GO1515

# DIMENSIONS



#### SOLDERING RECOMMENDATIONS

#### **Reflow Conditions**

The device will meet the data sheet specifications after completing the reflow process according to the profile shown in Figure 3. Do not reflow the device more than twice.

#### **Endurance To Warp**

When the device is soldered on a printed circuit board (dimension: 100mm x 100mm; thickness: 1.6mm) and the PCB is warped as shown in Figure 2, the device will not be cracked or damaged.

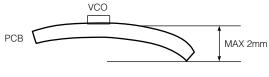


Fig. 3 PCB Warp

#### **Soldering Conditions**

Recommended soldering conditions are as follows:

#### **Reflow Soldering**

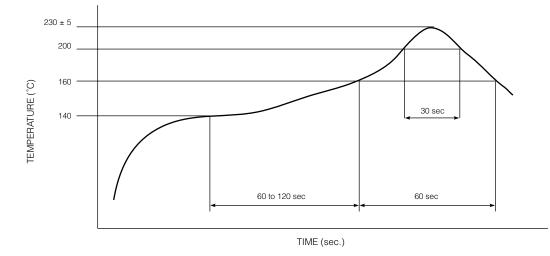
Preheating	150±10°C, 60 to 120 sec.
Soldering	Peak 230±5°C
	Over 200°C within 30 sec.

## Soldering Flux

Do not use cleaning type flux. Washing the devices after using cleaning type flux may damage inner parts and affect performance.

#### Solder Type

Use solder H60, H63 (in JIS Z 3282) or an equivalent type. This also applies to solder paste.





#### HANDLING RECOMMENDATIONS

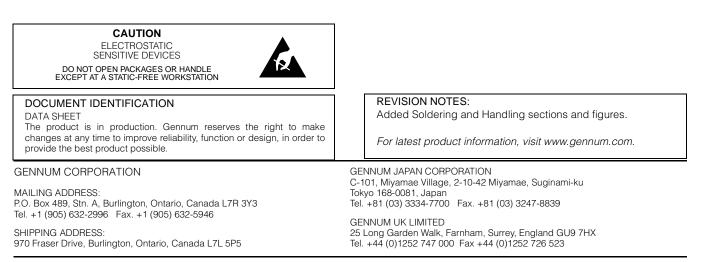
#### Cleaning

Do not wash the devices.

#### Storage

Store the devices out of direct sunlight, at a stable temperature and humidity. Avoid extreme temperatures, high humidity and wide temperature fluctuations. Condensation on the devices may result in reduced quality and lowered solderability. Use within 6 months after delivery. If the devices are stored for more than one year, solderability may be degraded.

Avoid dust, sea breezes and corrosive gases (Cl<sub>2</sub>, NH<sub>3</sub>, SO<sub>2</sub>, NO<sub>X</sub>, etc.).



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